Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model **[List multiple models if applicable.]**
ProCurve 10-GbE X2-SC SR Optic Transceiver (J8436A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	1
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants	Printed Circuit board, 2-4 small plastic encap ICs	4
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers	Printed Circuit board has fiberglass embedded in epoxy	1
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Phillips head screw driver	small head
Flat blade screw driver	small
Flat blade screw driver	Large

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Finisar Product Code: V23833-E6024-A103:
2.
3. Pry back 2 tabs on top and 2 tabs on bottom of plastic pull latch.
4. Pull off pull latch and remove metal retaining latches on front left and right of module.
5. Remove 4 small Philips head screws. If screws become stripped, the screws can be drilled out.
6. Using large blade screwdriver separate top and bottom section of metal shell. This may require some force as some components have thermal glue that attaches them to the top of the shell.
7. Remove PCBA and Optical Sub Assemblies.
8. Optical Sub Assemblies can be removed with small wire cutters.
9.
10. Merge Optics version:
11.
12. Remove 4 screws from X2 latch mechanism
13. Remove 4 screws connecting the top and base metal case
14. Separate the metal housing, SC plastic latches and PCB.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).